ADI Known Good Die (KGD)

ADI KGD
Capability:
• Tested to Full Data Sheet Specs (Zero PPM)
• Probing at Temperature (-60°C > 190°C)
• Die Thicknesses from 70µm
• Die Sizes from 500µm²
• Full Traceability for each Die Shipped
• Auto Inspection Options
• Outlier Removal Options

Shipping Options:
• Reconstituted Die on Film Frame
• Sawn Wafer on Film Frame
• Waffle Pack
• Tape and Reel

• Certified to ISO9001:2008 and ISO/TS16949
In today’s technologically driven world there is an ever-increasing demand for portable, hand-held, reduced-scale electronic equipment. Products tend to be lighter, thinner and faster, but their functionality continues to expand and develop at high intensity.

This drive for miniaturisation of portable products, in conjunction with decreased cost requirements and space reduction in larger products, is paving the way not only for Wafer Level Chip Scale packages (WLCSP), Flip Chips etc., but also, Bare Die. Customer demand for increased reliability has greatly contributed to the requirement of what is termed: Known Good Die (KGD).

ADI has been offering Known Good Die (KGD) since mid 2006. Our KGD processes allow for the shipment of product in die format to exceptionally high quality and reliability standards.

The objective of KGD is to supply die products that meet full product specification (at-speed function test, burn-in process and PPM level defects, over the entire temperature range).

The innovative Known Good Die manufacturing process at ADI is an ideal solution for customers whose applications demand zero defects. ADI employs a unique delivery process whereby KGD parts are tested to Full Data Sheet Specification, post singulation.

Refer to link below for the full listing of ADI released KGD products. Please note: The majority of ADI’s Standard Product Portfolio can be provided in KGD Format.

http://mil-aero.analog.com/static/imported-files/microsites/Mil_Aero/KnownGoodDie.pdf

If you require a KGD Part please email: KGD_Sales_Support@analog.com